Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{RM}	10	V
Average Rectified Output Current	I_O	4	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	35	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case (Note 5)	$R_{\theta JC}$	6	°C/W
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	65	°C/W
Operating Temperature Range $V_R \le 80\% V_{RRM}$ $V_R \le 50\% V_{RRM}$ DC Forward Mode (Note 7)	T_J	-55 to +150 ≤+175 ≤+200	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop (Note 6)	V_F	—	—	0.500	V	I_F = 4A, T_J = +25°C
Leakage Current (Note 6)	I_R	— —	— 6.5	200 —	μA mA	V_R = 10V, T_J = +25°C V_R = 10V, T_J = +125°C

Notes: 5. Device mounted on FR4 PCB pad layout 1inch 2oz copper
6. Short duration pulse test used to minimize self-heating effect.
7. Max junction temperature guaranteed for two hours.

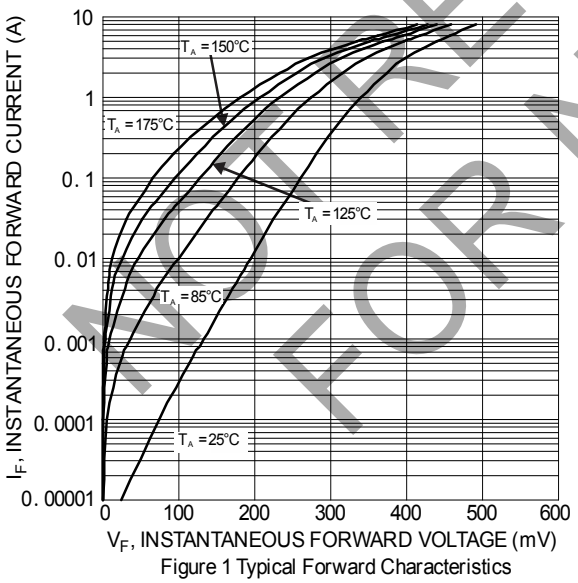


Figure 1 Typical Forward Characteristics

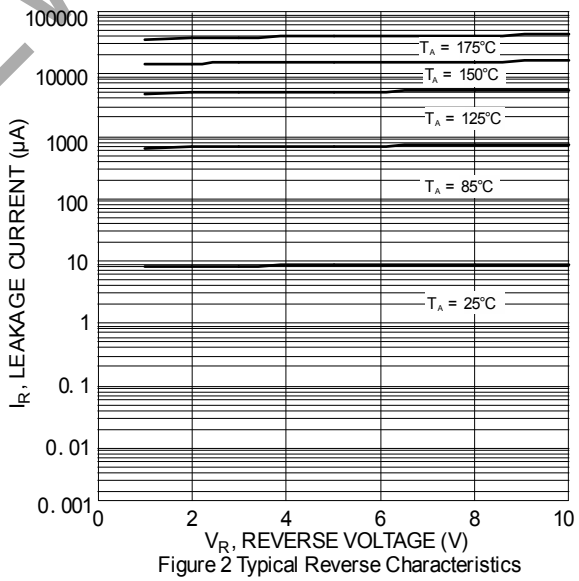


Figure 2 Typical Reverse Characteristics

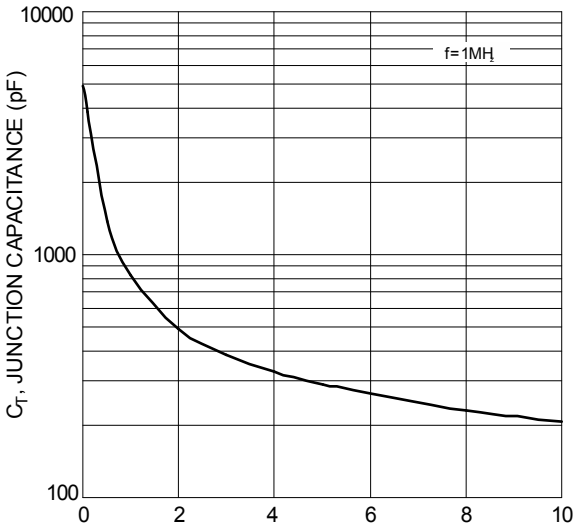


Figure 3 Typical Junction Capacitance

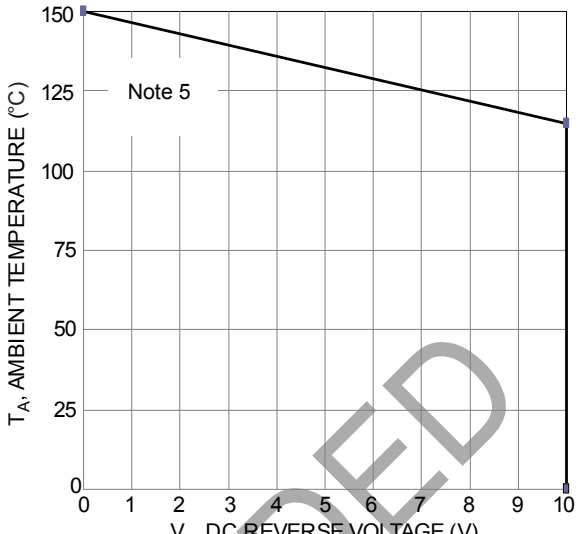


Figure 4 Operating Temperature Derating

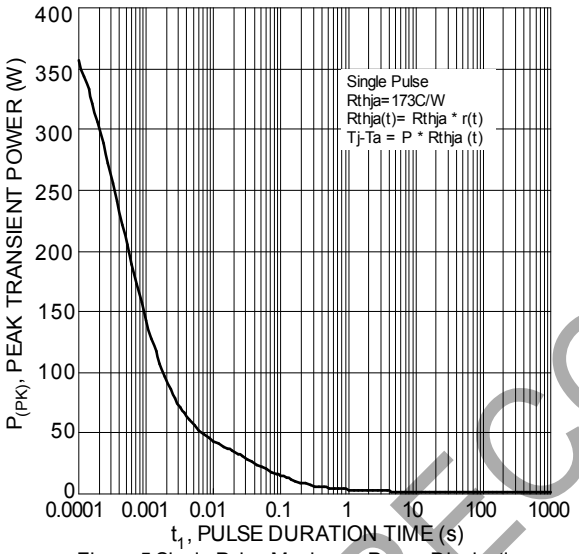


Figure 5 Single Pulse Maximum Power Dissipation

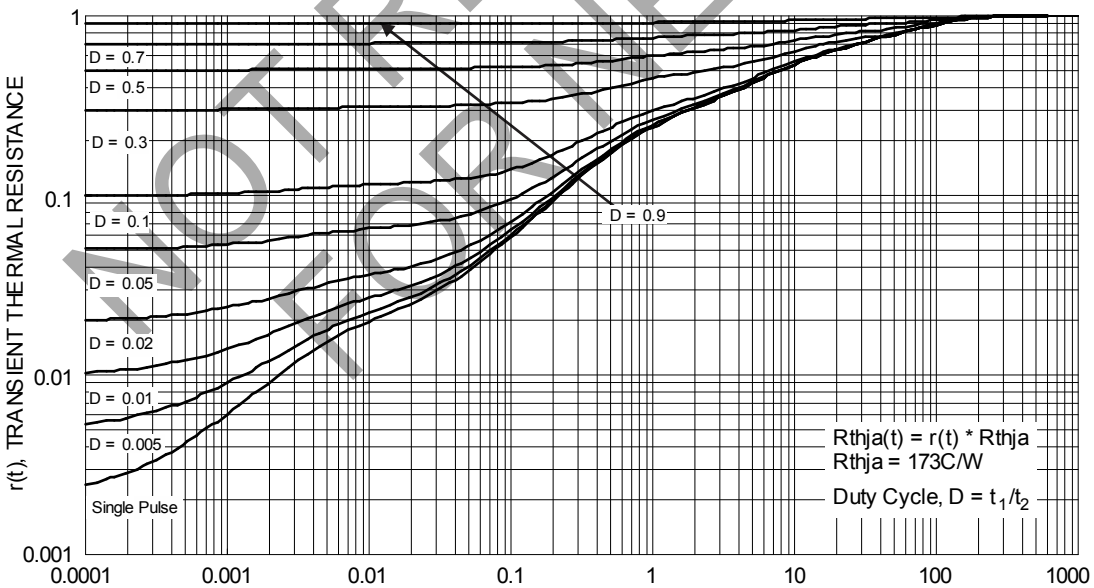
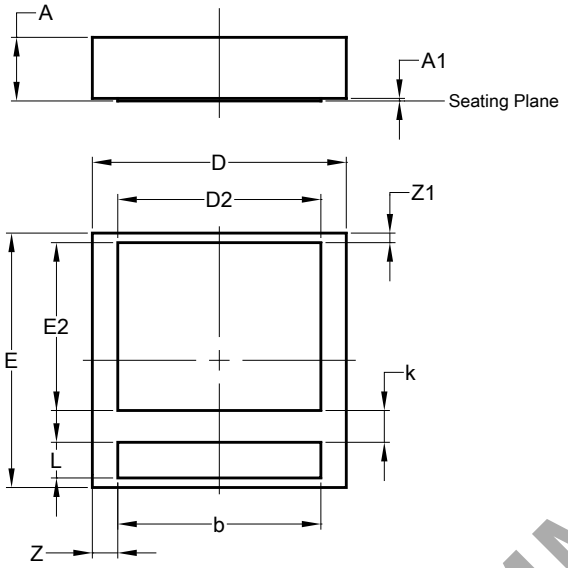


Figure 6 Transient Thermal Resistance

Package Outline Dimensions

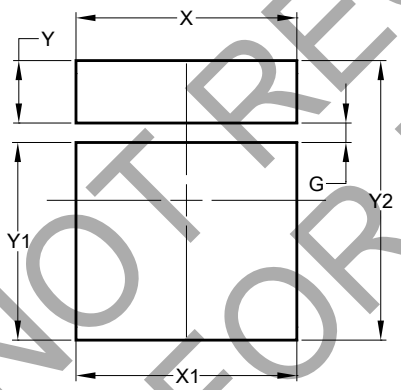
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



U-DFN2020-2 (Type B)			
Dim	**Min**	**Max**	**Typ**
A	0.47	0.53	0.50
A1	0.00	0.05	0.02
b	1.55	1.65	1.60
D	1.95	2.05	2.00
D2	1.50	1.70	1.60
E	1.95	2.05	2.00
E2	1.22	1.42	1.32
k	0.25 BSC		
L	0.23	0.33	0.28
Z	0.20 BSC		
Z1	0.075 BSC		
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	0.150
X	1.700
X1	1.700
Y	0.480
Y1	1.520
Y2	2.150

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